

# GL550/GL551

**High Speed Response Infrared Emitting Diode**

## ■ Features

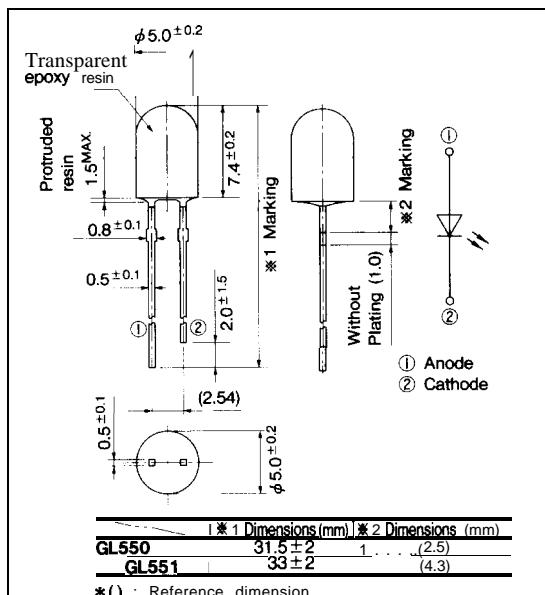
1. High speed response  
fc:TYP. 12 MHz
2. Intermediate beam angle  
GL550 A  $\theta$  : TYP.  $\pm 22^\circ$   
Narrow beam angle  
**GL551**  $\Delta\theta$  : TYP.  $\pm 10^\circ$
3. High output type  
Output : MIN. 10mW

## ■ Applications

1. IR data communication
2. Personal computer
3. Audio equipment
4. AV equipment

## ■ Outline Dimensions

(Unit : mm)



## ■ Absolute Maximum Ratings ( $T_a = 25^\circ C$ )

Parameter	Symbol	Rating	unit
Forward current	I <sub>F</sub>	50	mA
* <sup>1</sup> Peak forward current	I <sub>FM</sub>	0.5	A
Reverse voltage	V <sub>R</sub>	4	v
Power dissipation	P	140	mW
Operating temperature	T <sub>opr</sub>	-20 to +85	°C
Storage temperature	T <sub>stg</sub>	-30 to +85	°C
* <sup>2</sup> Soldering temperature	T <sub>sol</sub>	260	°C

\*1 Pulse width : 100  $\mu s$ , duty ratio : 0.01

\*2 For MAX. 3 seconds at the position of 3.0mm from the bottom face of resin package

## ■ Electro-optical Characteristics

(Ta = 25°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	unit
Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 50mA		1.5	2.0	v
Reverse current	I <sub>R</sub>	V <sub>R</sub> = 3V	—	—	10	μA
Terminal capacitance	C <sub>t</sub>	V <sub>R</sub> = 0, f = 1MHz	—	70	—	pF
Radiant flux	Φ <sub>e</sub>	I <sub>F</sub> = 50mA	10	—	35	mW
Peak emission wavelength	λ <sub>p</sub>	I <sub>F</sub> = 50mA	—	880	—	nm
Spectrum radiation bandwidth	△λ	I <sub>F</sub> = 50mA	—	40	—	nm
Half intensity angle	△θ	I <sub>F</sub> = 50mA	—	±22	—	
			—	±10	—	
Cut-off frequency	*f <sub>c</sub>	I <sub>F</sub> = 50mA + 10mA <sub>p-p</sub>		12	—	MHz

\*3 The value when modulation radiant flux drops 3dB from the reference (f = 100kHz)

1 Forward Current vs.  
Ambient Temperature

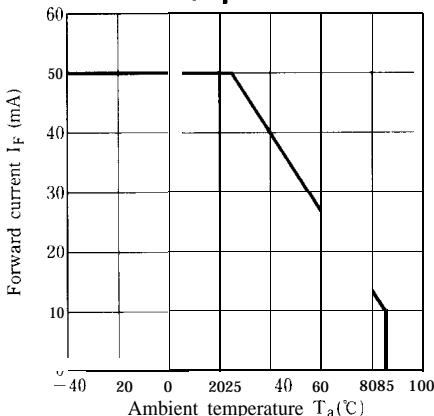
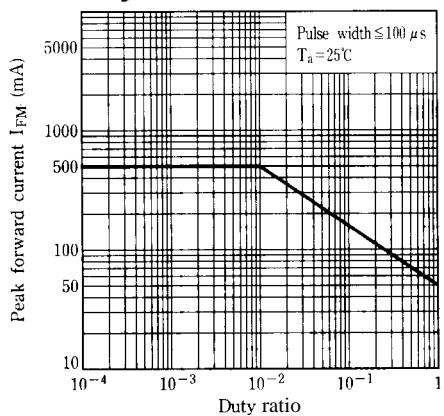


Fig. 2 Peak Forward Current vs.  
Duty Ratio



- Please refer to the chapter "Precautions for Use." (Page 78 to 93)